



Material Content Data Sheet



Sales Product Name		BGA 416 E6327		Issued		24. January 2018		
MA#		MA001351572						
Package		PG-SOT143-4-1		Weight*		11.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.004	0.03		346	
	non noble metal	tin	7440-31-5	0.001	0.01		89	
	inorganic material	silicon	7440-21-3	0.028	0.26	0.30	2567	3002
leadframe	non noble metal	nickel	7440-02-0	1.673	15.11		151098	
	non noble metal	iron	7439-89-6	2.310	20.87	35.98	208659	359757
wire	noble metal	gold	7440-57-5	0.017	0.16	0.16	1564	1564
encapsulation	organic material	carbon black	1333-86-4	0.104	0.94		9415	
	inorganic material	antimonytrioxide	1309-64-4	0.156	1.41		14123	
	plastics	brominated resin	-	0.195	1.77		17654	
	plastics	epoxy resin	-	1.629	14.71		147117	
	inorganic material	silicondioxide	60676-86-0	4.430	40.01	58.84	400158	588467
leadfinish	non noble metal	tin	7440-31-5	0.219	1.98	1.98	19811	19811
plating	noble metal	silver	7440-22-4	0.303	2.74	2.74	27399	27399
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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